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**WEI et al.**(10) **Pub. No.: US 2022/0369475 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **CIRCUIT BOARD, METHOD FOR  
MANUFACTURING THE SAME****Publication Classification**(71) Applicants: **Avary Holding (Shenzhen) Co.,  
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**2201/09372** (2013.01)(72) Inventors: **YONG-CHAO WEI, Qinhuangdao  
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(TW)**(57) **ABSTRACT**

A circuit board includes a circuit substrate, a solder, and a surrounding portion. The circuit substrate includes a connecting pad. The solder is formed on a surface of the connecting pad. The surrounding portion is formed on the surface of the connecting pad and cooperates with the connecting pad to form a groove receiving the solder. The surrounding portion surrounds the solder and is spaced from the solder. A method for manufacturing a circuit board is also provided.

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